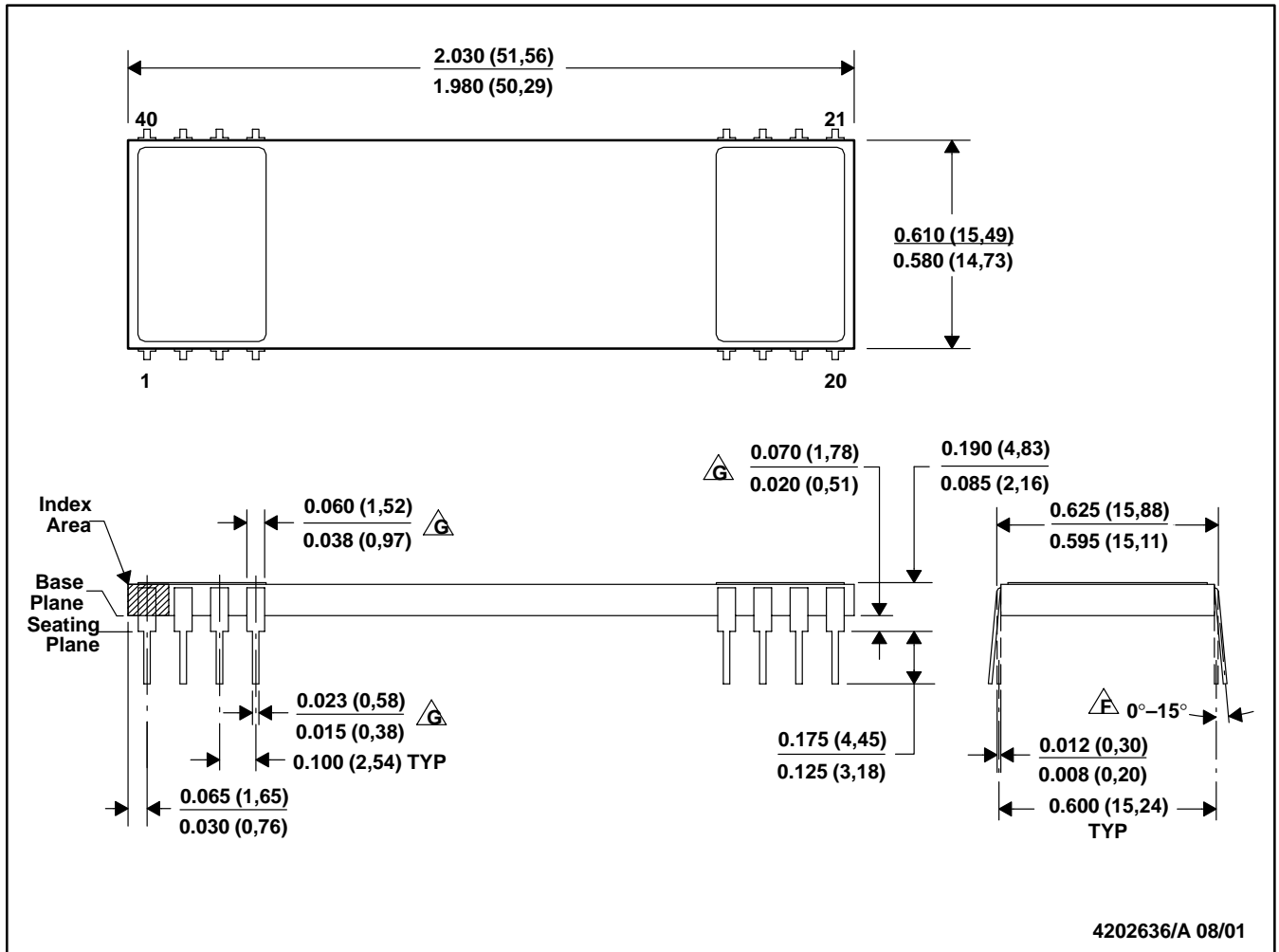


JVD (R-CDIP-T16/40)

CERAMIC SIDE-BRAZE DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Controlling dimension: inch.  
 D. Falls within JEDEC MO-038-AC with the exception of lead count.  
 E. Leads within 0.005 (0,13) radius of true position (TP) at gage plane with maximum material condition and unit installed.  
 F. Angle applies to spread leads prior to installation.  
 G. Outlines on which the seating plane is coincident with the plane (standoff = 0), terminals lead standoffs are not required, and lead shoulder may equal lead width along any part of the lead above the seating/base plane.  
 H. A visual index feature must be located within the cross-hatched area.

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